Abstract

Simultaneous double-side grinding of semiconductor wafers

The invention relates to a method for the correction of the grinding spindle positions in double-side grinding machines for the simultaneous double-side machining of semiconductor wafers, wherein the two grinding spindles, each comprising a grinding disk flange for receiving a grinding disk, are coupled torsionally by means of a coupling element and a measuring unit, comprising an inclinometer and two sensors for distance measurement, is mounted instead of grinding disks between the two grinding disk flanges in such a way that the grinding spindles are in this case essentially in the position in which they are situated with mounted grinding disks during the grinding process, wherein the coupled grinding spindles are rotated while inclinometer and sensors are used to determine radial and axial correction values of an axial alignment of the two grinding spindles which are used for a symmetrical orientation of the two grinding spindles. A further aspect of the invention relates to corrections of the spindle positions under the action of process forces. Further claims are directed at devices for carrying out the methods.

Fig. 1